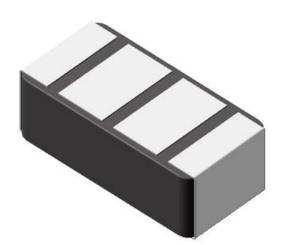


#### **TECHNICAL DATA SHEET**

Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G



## Features:

- Frequency 2400-2483.5MHz
- Size 3.2 x 1.6 x 1.1mm
- Efficiency >80%
- Gain >1.5dBi
- SMD compatible
- MSL 3

# **Applications:**

- 2.4GHz ISM band radios
- · Bluetooth, BLE
- WiFi 2.4GHz
- IoT, M2M devices

All dimensions are in mm / inches

Issue: 1905

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

Series: Ceramic Chip Antenna

## **ELECTRICAL SPECIFICATIONS**

Antenna Type	Ceramic Chip
Frequency	2400-2483.5MHz
Nominal Impedance	50 $\Omega$
VSWR	<1.6:1
Radiation Pattern	Omni
Gain	>1.5dBi
Efficiency	>80%
Polarization	Linear
Power Withstanding	2W

## **MECHANICAL SPECIFICATIONS**

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	3

## **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature	-40 / +85 ° C
Storage Temperature	-40 / +85 ° C
RoHS Compliant	Yes

2



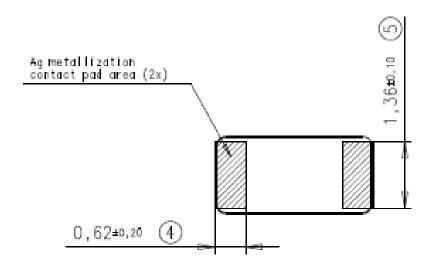


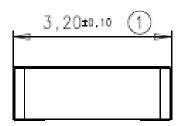
Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

Series: Ceramic Chip Antenna

## **MECHANICAL DRAWING**





Antenna features		
No.	Terminal Name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm
Antenna is symmetrical.		
Either of terminals 1 or 2 can be Feed / GND		



Description: 2.4GHz Ceramic Chip Antenna

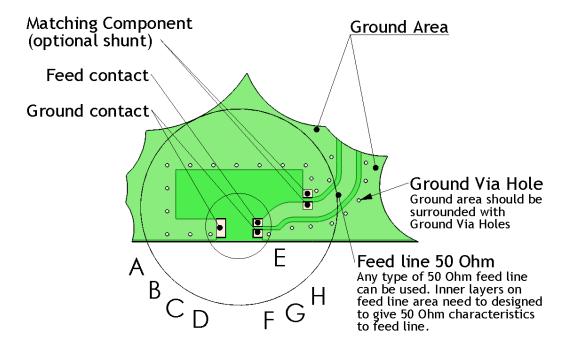
PART NUMBER: W3008G

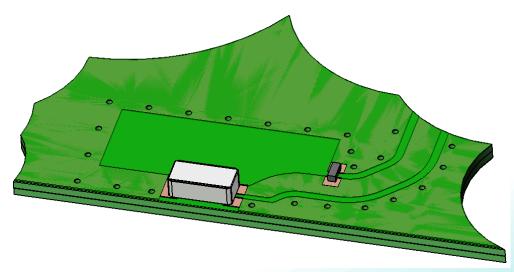
Series: Ceramic Chip Antenna

## **OTHER SPECIFICATIONS**

## **PWB** Layout

Typical performance (test board size 80x37 mm, PWB ground clearance area 11.00 x 6.25 mm) Antenna placed 80mm edge center position.











**Description**: 2.4GHz Ceramic Chip Antenna

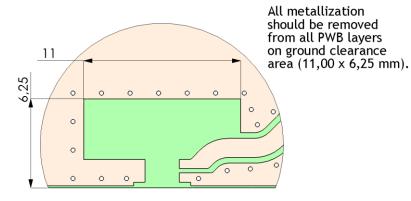
PART NUMBER: W3008G

Series: Ceramic Chip Antenna

## **OTHER SPECIFICATIONS**

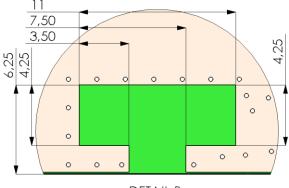
Ground cleared under antenna, clearance area 11.00 x 6.25 mm

Ground clearance area (11,00 x 6,25 mm)



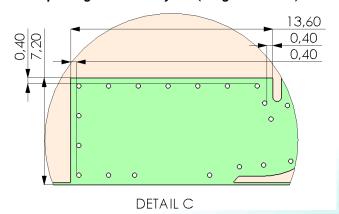
**DETAIL A** 

#### Opening in bottom/inner ground layers



DETAIL B

#### Opening in other layers (no ground/ RF)







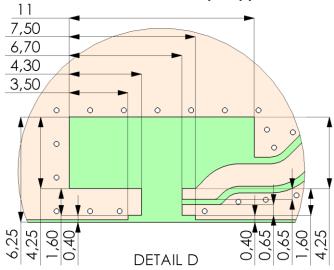
**Description**: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

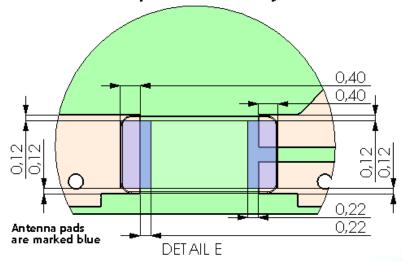
## **OTHER SPECIFICATIONS**

PWB pad dimensions and antenna position

### Pad dimensions in top copper



#### Antenna position on PWB layout





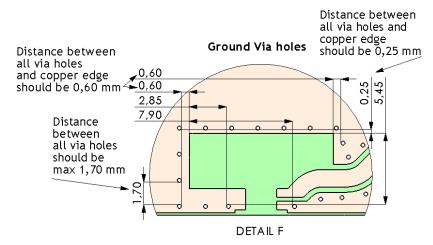


**Description**: 2.4GHz Ceramic Chip Antenna

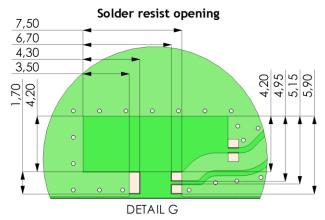
PART NUMBER: W3008G

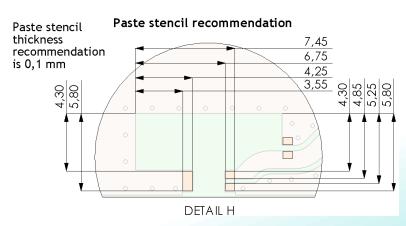
## **OTHER SPECIFICATIONS**

## Typical Ground via hole placement in PWB layout



Solder resist opening and paste stencil recommendations







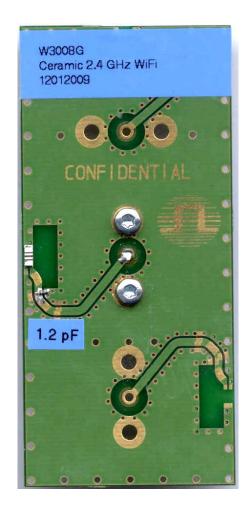
**Description**: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

# Series: Ceramic Chip Antenna

## **TEST SETUP**

All RF parameters measured on 37x80mm evaluation board. Antenna placement on side center position of PCB long edge. Shunt 1.2pF capacitor for matching.





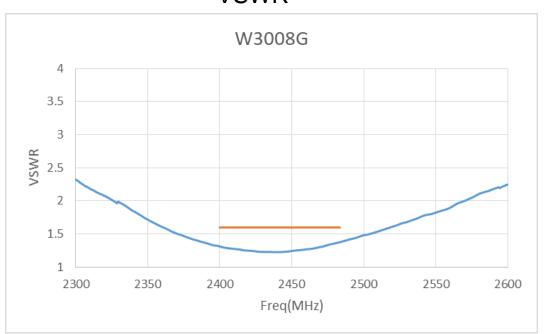
Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

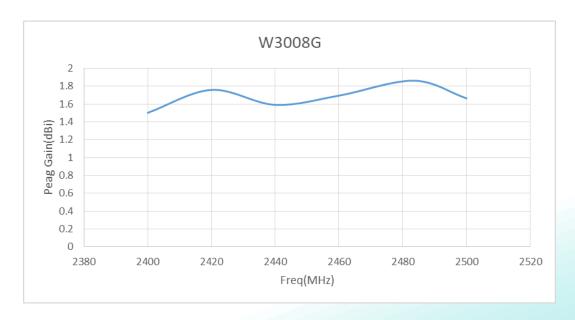
Series: Ceramic Chip Antenna

### **CHARTS**

## **VSWR**



# Peak Gain



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ROHS





**Description**: 2.4GHz Ceramic Chip Antenna

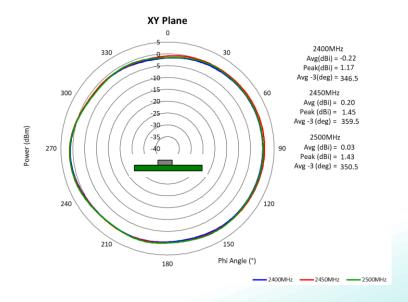
PART NUMBER: W3008G

### **CHARTS**

# **Radiation Efficiency**



# Radiation pattern X-Y plane





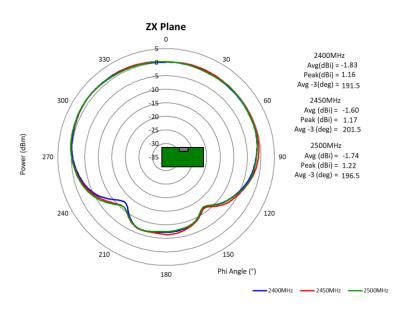


**Description**: 2.4GHz Ceramic Chip Antenna

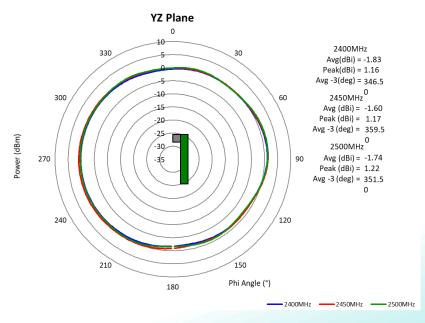
PART NUMBER: W3008G

### **CHARTS**

# Radiation pattern Z-X plane



# Radiation pattern Y-Z plane







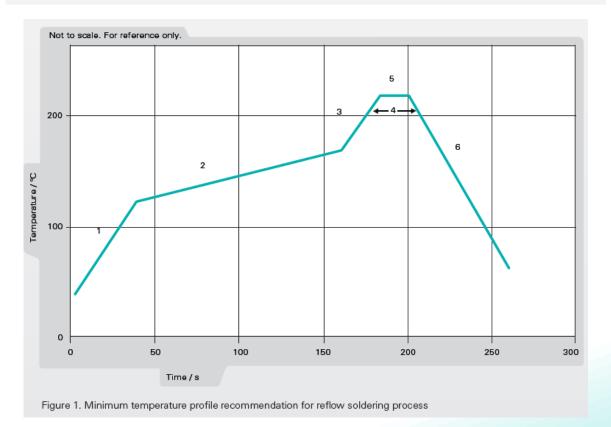
Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

## Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



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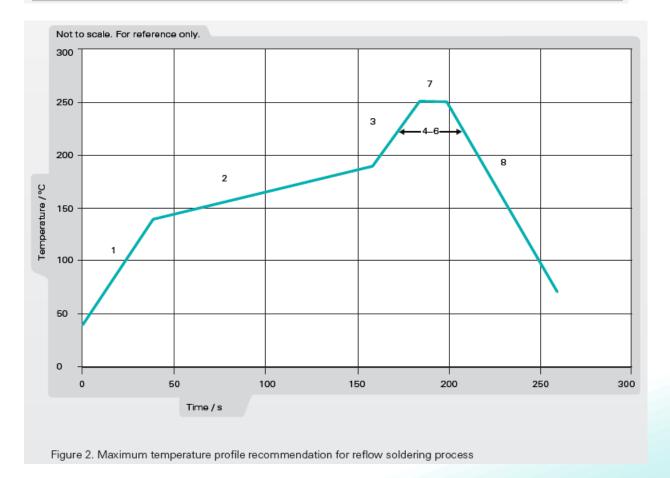


**Description**: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

# **Recommendation for reflow soldering process**

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s







**Description**: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

# Series: Ceramic Chip Antenna

### **PACKAGING**

